

FIGURE 1

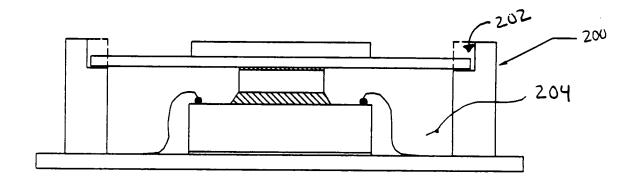


FIGURE 2

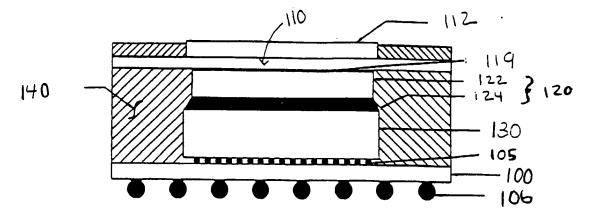


FIGURE 3

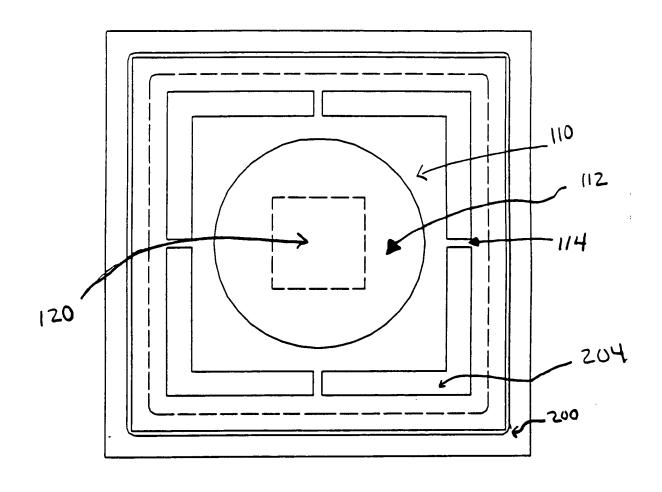


FIG. 4A

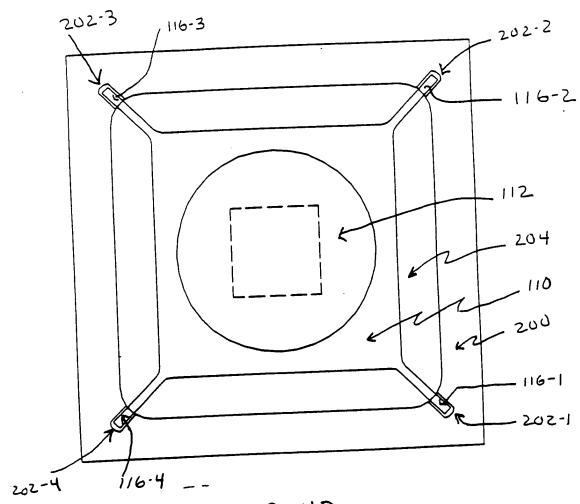
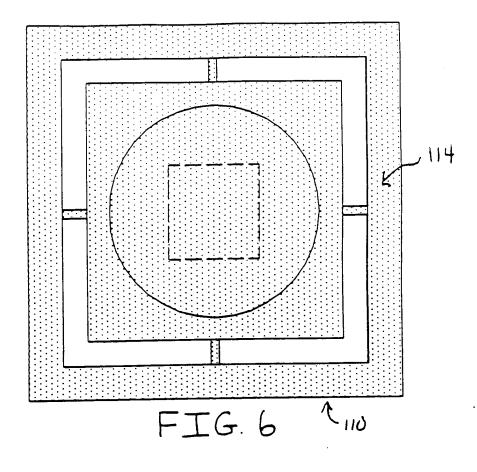


FIG. 4B

FIG.5.



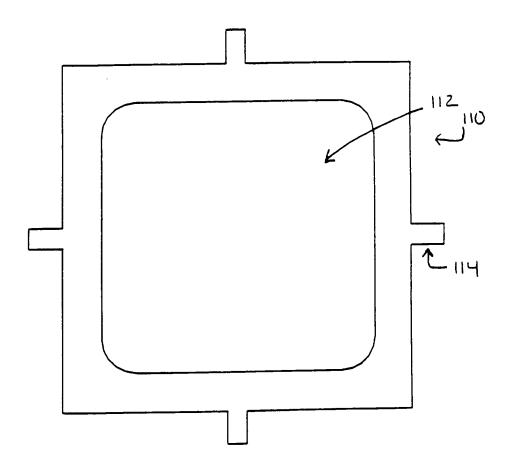
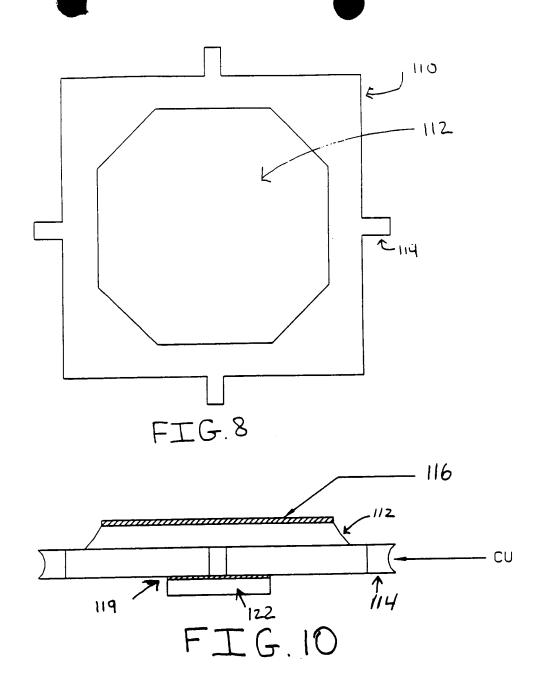


FIG.7



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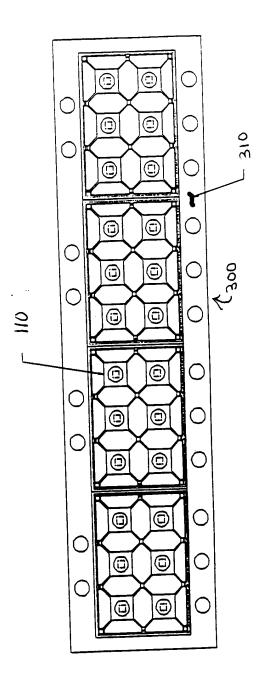


FIG.9B

INSTALL CARRIER ON SUBSTRATE 1110

ATTACH SEMICONDUCTOR DIE TO SUBSTRATE

1115

ALIGN HEAT SINK OVER SEMICONDUCTOR DIE

1120

BRING HEAT SINK TO REST ON CARRIER

1125

ENCAPSULATE CAVITY LEAVING SUBSTANTIAL
PORTION OF HEAT SINK EXPOSED TO ENVIRONMENT

1130

SINGULATE PREPACKAGES INTO PACKAGES WITH A PORTION OF HEAT SINK EXPOSED TO ENVIRONMENT 1135

FIG. 11